

REMARKS

Status of the Claims

Claims 1-16 are pending in the application, of which claims 14-16 are withdrawn from consideration.

The Present Claims Are Patentable Over Kobayashi

In paragraph 5, on page 3 of the Office Action, claims 1-13 were rejected under 35 U.S.C. § 102(b) as anticipated by, or in the alternative, under 35 U.S.C. § 103(a) as obvious over, Kobayashi (JP Application No. 2004/071473).

Applicants traverse.

For at least the following reasons, Kobayashi does not disclose or fairly suggest the presently claimed patterned substrate having a conductor pattern thereon.

(1) The Examiner appears to allege that Kobayashi discloses an organic polysilane as a material for a wettability variable layer. The Examiner's characterization of Kobayashi is in error. Kobayashi does not disclose an "organic polysilane." Instead, Kobayashi discloses an "organopolysiloxane." Although Kobayashi mentions various silane compounds in paragraphs [0028]-[0032] and [0086], these silane compounds are only used as starting monomers to prepare organopolysiloxanes.

Clearly, the polysiloxane compounds are not polysilanes, since polysilanes are polymers having Si-Si bonds, while polysiloxanes are polymers having Si-O-Si bonds.

(2) In addition, Table 1 and Illustration 1 set forth on the following pages summarize a brief comparison between the patterned substrate of the claimed invention and the patterned substrate of Kobayashi. Table 1 and Illustration 1 are meant for illustrative purposes only and should not be considered as enlarging or narrowing the scope of the claimed invention.

RESPONSE UNDER 37 C.F.R. § 1.111
U.S. Application No. 10/594,840 (Q97512)

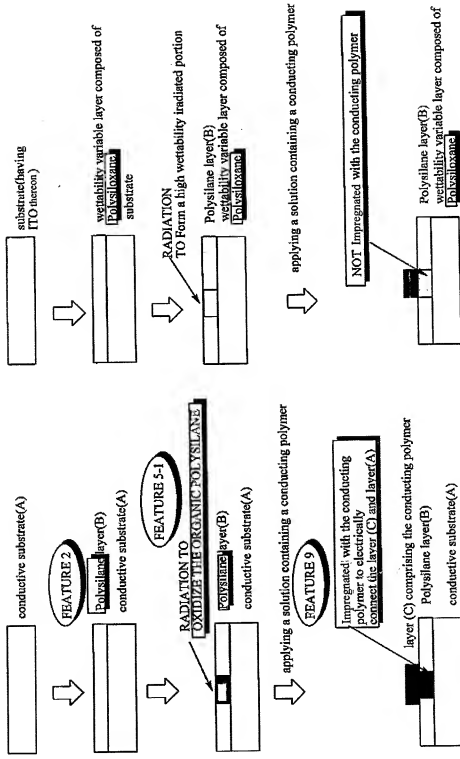
Table 1

Element	Claim Recitation	Example Disclosure of Kobayashi	Does Kobayashi disclose or suggest this claim element?
Element 1	A patterned substrate having a conductor pattern obtained by:	A patterned substrate formed by:	
Element 2	forming layer (B)	Forming a wettability variable layer	
Element 3	comprising an <u>organic polysilane</u>	Comprising a <u>polysiloxane</u> that is not an organic polysilane	NO
Element 4	on conductive substrate (A);	on a substrate (having ITO);	
Element 5	irradiating a certain region of the layer (B) with a radiation	irradiating the wettability variable layer with ultraviolet ray through a mask	
Element 5-1	to oxidize the organic polysilane constituting the layer (B) in the certain region; and then	to enhance the wettability of the irradiated region	NO
Element 6	applying a solution containing a conducting polymer, water, and/or a hydrophilic solvent	applying a hydrophilic solution containing polyaniline, polythiophene or the like	
Element 7	at least on the certain region of the layer (B)	on the irradiated region	
Element 8	to form layer (C) comprising the conducting polymer,	to form a layer comprising polyaniline, polythiophene or the like.	
Element 9	while impregnating the layer (B) in the certain region with the conducting polymer to electrically connect the layer (C) and the substrate (A).		NO

ILLUSTRATION I

Outline of Present Claims

Kobayashi



As can be seen above, Kobayashi fails to disclose or suggest at least elements 3, 5-1 and 9 of the claimed invention. Accordingly, the claimed invention is patentable over Kobayashi.

(3) In paragraph 7, on page 4 of the Office Action, the Examiner asserts that the processes of forming the patterned substrate recited in claims 1-7 are not essential to a determination of patentability of the composition disclosed in the claim. In addition, the Examiner asserts that none of the limitations recited in claims 1-7 impact a structural property in the end product of their claimed patterned substrate.

Applicants disagree.

As described above, the patterned substrate of the claimed invention differs from the patterned substrate of Kobayashi in the type of materials constituting layer (B). Polysilane is used in layer (B) of the claimed invention, and polysiloxane is used in Kobayashi.

Further, the patterned substrate of the claimed invention has the layer (C) electrically connected to the substrate (A). This point alone distinguishes the claimed invention from Kobayashi because the latter does not have the wettability variable layer and the substrate electrically connected.

Accordingly, it would be readily apparent to one of ordinary skill in the art that the patterned substrate of the claimed invention is different from that of Kobayashi in the type of materials used as well as in its structure. Thus, the Examiner's allegation that that none of the limitations in claims 1-7 impact a structural property in the end product is clearly in error.

In view of the above, Applicants request reconsideration and withdrawal of the rejection of claims 1-13 based on Kobayashi.

In paragraph 8, on page 4 of the Office Action, claim 11 was rejected under 35 U.S.C. § 103(a) as being unpatentable over Kobayashi in view of Veres (WO 2004/013922).

Applicants traverse.

Claim 11 depends from claim 1 and is patentable over Kobayashi in view of Veres in view of its dependency for the reasons set forth above and the additional elements recited therein.

In view of the above, Applicants request reconsideration and withdrawal of the rejection of claim 11 based on Kobayashi in view of Veres.

Conclusion

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited.

If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the local, Washington, D.C., telephone number listed below.

The U.S. Patent and Trademark Office is hereby directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

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